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MTFC8GLWDM-3M AIT Z

SPECS

ROHS CERTIFICATES DOCUMENTATION & SUPPORT

PARTS WITH THE SAME DATA SHEET (4)

WHERE TO

Data Sheets (1)

Data Sheet

4-32GB eMMC v4.51 TFBGA153 & TFBGA169 (Automotive, IT) Data Sheet

MTFC4GMWDM-3M AIT, MTFC8GLWDM-3M AIT Z, MTFC8GLWDM-AIT Z, MTFC16GLWDM-4M AIT Z, MTFC32GJWEF-4M AIT Z (Controller ID= W)

File Type: PDF

Updated: 07/2015

Automotive **Embedded Memory Solutions** eMMC Managed NAND

VIEW

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Specs

Orderable Parts for: MTFC8GLWDM-3M AIT Z

SEE ALL 8GB E.MMC MEMORY PARTS

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MTFC8GLWDM-3M AIT Z	Production	N/A	HBBSN	N/A	N/A	No		N/A

Detailed Specifications

Part Status Code	Production	Applications	Automotive	Density	8GB	Bus Width	x8
Voltage	2.7V-3.6V	Package	TFBGA	Pin Count	153-ball	Package Size	11.5 x 13 x 1.2
MMC Interface	4.5	RoHS	Yes	Operating Temp	-40C to +85C		

RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

MTFC8GLWDM 3M AIT Z

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2002/95/EC, a.k.a. Restriction of Hazardous Substances (RoHS) Directive.

File Type: (PDF)

Updated: 02/2017

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RoHS Certificates

China RoHS Certificate (PDF)

MTFC8GLWDM 3M AIT Z

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

File Type: (PDF)

Updated: 02/2017

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Documentation & Support

See All Documentation

Technical Notes

SEARCH (54) TECHNICAL NOTES

Technical Notes

TN-00-08: Thermal Applications (PDF)

DRAM Managed NAND Multichip Packages NAND Flash See More Tags

(TN-00-08) Describes some considerations in thermal applications for Micron memory devices

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File Type: PDF

Updated: 01/24/2017

Technical Notes



TN-13-49: SLC NAND Device Refresh (PDF)

NAND Flash SLC NAND

(TN-13-49) This technical note discusses the adverse effects of high temperature and PROGRAM/ ERASE (P/E) cycles on flash memory data retention and how the REFRESH operation can be used to mitigate these adverse effects.

File Type: PDF

Updated: 10/31/2016

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Technical Notes

TN-29-14: NAND Flash Performance Increase Using PROGRAM PAGE CACHE MODE Command (PDF)

NAND Flash

(TN-29-14) This technical note highlights the significant performance gains realized when using the PROGRAM PAGE CACHE MODE command in Micron's NAND Flash devices.

File Type: PDF

Updated: 09/29/2016

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Technical Notes

TN-29-25: Improving NAND Flash Performance Using Two-Plane Command Enabled Micron Devices (PDF)

NAND Flash

(TN-29-25) This technical note describes the performance benefits of Micron two-plane commands and provides implementation guidelines for making the best use of two-plane capabilities.

File Type: PDF

Updated: 09/29/2016

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Technical Notes

TN-29-42: Wear-Leveling Techniques in NAND Flash Devices (PDF)

NAND Flash

(TN-29-42) This technical note highlights the importance of wear leveling, explains two wear-leveling techniques, and discusses implementing wear leveling.

File Type: PDF

Updated: 09/29/2016

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SEARCH (54) TECHNICAL NOTES

Customer Service Note

Customer Service Note

Customer Service Note

Shipping Quantities (PDF)

DRAM DRAM Modules Hybrid Memory Cube Multichip Packages See More Tags

(CSN-04) This customer service note describes the standard shipping quantity, box quantity, and types such as tape and reel for Micron's products.

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File Type: PDF **Updated:** 07/18/2016

Customer Service Note

Wafer Packaging and Packaging Materials (PDF)

DRAM NAND Flash

(CSN-20) Provides complete shipping and recycling information about each of the materials used for shipping Micron's products.

Downloaded from Arrow.com.

File Type: PDF Updated: 06/21/2016

SEARCH (2) CUSTOMER SERVICE NOTE

Parts with the same Data Sheet (4)

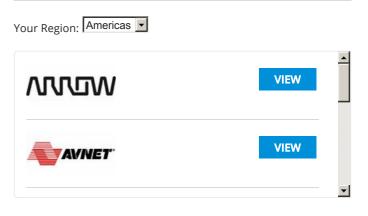
MTFC8GLWDM-3M AIT Z (Current)		MTFC4GMWDM-3M AIT	MTFC16GLWDM-4M AIT Z	MTFC32GJWEF-4M AIT Z		
Part Status Code	Production	Production	Production	Production		
Applications	Automotive	Automotive	Automotive	Automotive		
Density	8GB	4GB	16GB	32GB		
Bus Width	x8	x8	x8	x8		
Voltage	2.7V-3.6V	2.7V-3.6V	2.7V-3.6V	2.7V-3.6V		
Package	TFBGA	TFBGA	TFBGA	TFBGA		
Pin Count	153-ball	153-ball	153-ball	169-ball		
Package Size	11.5 x 13 x 1.2	11.5 x 13 x 1.2	11.5 x 13 x 1.2	14 x 18 x 1.2		
MMC Interface	4.5	4.5	4.5	4.5		
RoHS	Yes	Yes	Yes	Yes		
Operating Temp	-40C to +85C	-40C to +85C	-40C to +85C	-40C to +85C		

Where to Buy

Orderable Parts

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MTFC8GLWDM-3M AIT	Production	N/A	HBBSN	N/A	N/A	No		N/A

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NOR Flash

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